

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Byoung Hwa LEE</td> <td>12/09/2008</td> </tr> <tr> <td>Sung Kwon WI</td> <td>12/09/2008</td> </tr> <tr> <td>Hong Yeon CHO</td> <td>12/09/2008</td> </tr> <tr> <td>Dong Seok PARK</td> <td>12/09/2008</td> </tr> <tr> <td>Sang Soo PARK</td> <td>12/09/2008</td> </tr> <tr> <td>Min Cheol PARK</td> <td>12/09/2008</td> </tr> </tbody> </table>		Name	Execution Date	Byoung Hwa LEE	12/09/2008	Sung Kwon WI	12/09/2008	Hong Yeon CHO	12/09/2008	Dong Seok PARK	12/09/2008	Sang Soo PARK	12/09/2008	Min Cheol PARK	12/09/2008
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Sang Soo PARK	12/09/2008														
Min Cheol PARK	12/09/2008														
RECEIVING PARTY DATA															
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.														
Street Address:	314 Maetan3-Dong, Yeongtong-Gu														
City:	Suwon, Gyunggi-do														
State/Country:	REPUBLIC OF KOREA														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12339839</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12339839										
Property Type	Number														
Application Number:	12339839														
CORRESPONDENCE DATA															
Fax Number:	(202)756-8087														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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ATTORNEY DOCKET NUMBER:	069576-0481														
NAME OF SUBMITTER:	Stephen A. Becker														

CH \$40.00 12339839

Total Attachments: 3

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RECORDATION FORM COVER SHEET

Docket No.: 069576-0481

PATENTS ONLY

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)
Byoung Hwa LEE, Sung Kwon WI, Hong Yeon CHO, Dong Seok PARK, Sang Soo PARK, Min Cheol PARK

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: **SAMSUNG ELECTRO-MECHANICS CO., LTD.**
 Internal Address:

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): **December 9, 2008**

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

Address: **314 Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-do, REPUBLIC OF KOREA**

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):
 A. Patent Application No(s).

Additional numbers attached? Yes No

This document is being filed together with a new application.
 B. Patent No(s).

5. Name and address to whom correspondence concerning document should be mailed:

6. Total number of applications and patents involved: 1

Name: **MCDERMOTT WILL & EMERY LLP**
 Internal Address:
 Street Address: **600 13th Street, N.W.**
 City: **Washington** State: **D. C.** Zip: **20005-3096**
 Phone Number: **202.756.8000**
 Fax Number: **202.756.8087**
 Email Address:

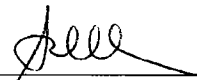
7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers _____
 Expiration Date _____

b. Deposit Account Number 500417
 Authorized User Name _____

9. Signature.
Stephen A. Becker 26,527  **December 19, 2008**

Name and Registration No. of Person Signing _____ Signature _____ Date _____

Total number of pages including cover sheet, attachments and documents: **3**

(SAB)

Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|----------------------------|----------------------------|
| (1) <u>LEE, Byoung Hwa</u> | (6) <u>PARK, Min Cheol</u> |
| (2) <u>WI, Sung Kwon</u> | (7) _____ |
| (3) <u>CHO, Hong Yeon</u> | (8) _____ |
| (4) <u>PARK, Dong Seok</u> | (9) _____ |
| (5) <u>PARK, Sang Soo</u> | (10) _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto SAMSUNG ELECTRO-MECHANICS CO., LTD.

314 Maetan3-Dong, Yeongtong-Gu, Suwon, Gyunggi-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled MULTILAYER CHIP CAPACITOR

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or


(b) for which an application for United States Letters Patent was executed on _____, and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;


AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

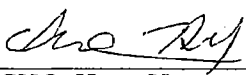
SIGNED on the dates indicated aside our signatures:

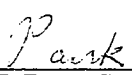
INVENTORS

DATE SIGNED

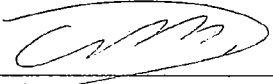
1) <u></u>	<u>2008. 12. 9</u>
Name: LEE, Byoung Hwa	

2) <u></u>	<u>2008. 12. 9</u>
Name: WI, Sung Kwon	

3) <u></u>	<u>2008. 12. 9</u>
Name: CHO, Hong Yeon	

4) <u></u>	<u>2008. 12. 09</u>
Name: PARK, Dong Seok	

5)



2008. 12. 9

Name: PARK, Sang Soo

6)



2008. 12. 9

Name : PARK, Min Cheol